ALPHA & OMEGA SEMICONDUCTOR

AOD3C50

500V,3A N-Channel MOSFET

General Description

- Trench Power AlphaMOS-II technology
- Low $R_{DS(ON)}$
- Low Ciss and Crss
- High Current Capability
- RoHS and Halogen Free Compliant

Applications

- General Lighting for LED and CCFL
- AC/DC Power supplies for Industrial, Consumer, and Telecom

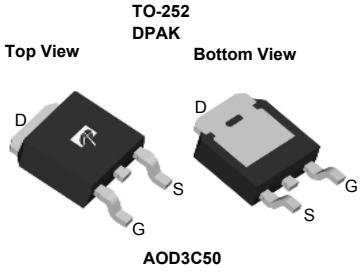
Product Summary

V_{DS} @ $T_{j,max}$	600V
I_{DM}	12A
$R_{DS(ON),max}$	< 1.4Ω
$Q_{g,typ}$	12nC
E_{oss} @ 400V	1.5µJ

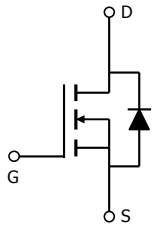
100% UIS Tested
100% R_g Tested

Green Product

TO-252
DPAK



AOD3C50



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOD3C50	TO-252	Tape & Reel	2500

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	500	V
Gate-Source Voltage		V_{GS}	±30	V
Continuous Drain Current	T_C=25°C	I_D	3*	A
	T_C=100°C		3	
Pulsed Drain Current [C]		I_{DM}	12	
Avalanche Current [C] L=1mH		I_{AR}	3	A
Repetitive avalanche energy [C]		E_{AR}	4.5	mJ
Single pulsed avalanche energy [H]		E_{AS}	152	mJ
MOSFET dv/dt ruggedness		dv/dt	100	V/ns
Peak diode recovery dv/dt			20	
Power Dissipation [B]	T_C=25°C	P_D	83	W
	Derate above 25°C		0.7	W/°C
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds		T_L	300	°C

Thermal Characteristics

Parameter	Symbol	Typical	Maximum	Units
Maximum Junction-to-Ambient [A,D]	$R_{\theta JA}$	45	55	°C/W
Maximum Case-to-sink [A]	$R_{\theta CS}$	-	0.5	°C/W
Maximum Junction-to-Case [D,F]	$R_{\theta JC}$	1.2	1.5	°C/W

* I_D limited by Rated I_D

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V, T_J=25°C	500			V
		I_D=250µA, V_{GS}=0V, T_J=150°C		600		
BV_{DSS} /ΔTJ	Breakdown Voltage Temperature Coefficient	I_D=250µA, V_{GS}=0V		0.4		V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=500V, V_{GS}=0V			1	µA
		V_{DS}=400V, T_J=125°C			10	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±30V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=5V, I_D=250µA	3	4.1	5	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=2.2A		1.1	1.4	Ω
g_{FS}	Forward Transconductance	V_{DS}=40V, I_D=1.5A		2.5		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.78	1	V
I_S	Maximum Body-Diode Continuous Current				3	A
I_{SM}	Maximum Body-Diode Pulsed Current [C]				12	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=100V, f=1MHz		662		pF
C_{oss}	Output Capacitance			26		pF
$C_{o(er)}$	Effective output capacitance, energy related [I]	V_{GS}=0V, V_{DS}=0 to 400V, f=1MHz		19		pF
$C_{o(tr)}$	Effective output capacitance, time related [J]			35		pF
C_{rss}	Reverse Transfer Capacitance	V_{GS}=0V, V_{DS}=100V, f=1MHz		9.7		pF
R_g	Gate resistance	f=1MHz		3		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	V_{GS}=10V, V_{DS}=400V, I_D=3A		12	25	nC
Q_{gs}	Gate Source Charge			3.4		nC
Q_{gd}	Gate Drain Charge			4.4		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=250V, I_D=3A, R_G=25Ω		21		ns
t_r	Turn-On Rise Time			28		ns
$t_{D(off)}$	Turn-Off DelayTime			32		ns
t_f	Turn-Off Fall Time			21		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=3A,dI/dt=100A/µs,V_{DS}=100V		260		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=3A,dI/dt=100A/µs,V_{DS}=100V		2.3		µC

A. The value of R_{qJA} is measured with the device in a still air environment with T_A=25°C.
B. The power dissipation P_D is based on $T_{J(MAX)}$=150°C in a TO252 package, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150°C.
D. The R_{qJA} is the sum of the thermal impedance from junction to case R_{qJC} and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300 ms pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=150°C.
G.These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.
H. L=60mH, I_{AS}=2.25A, V_{DD}=150V, R_G=10Ω, Starting T_J=25°C.
I. $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$.
J. $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

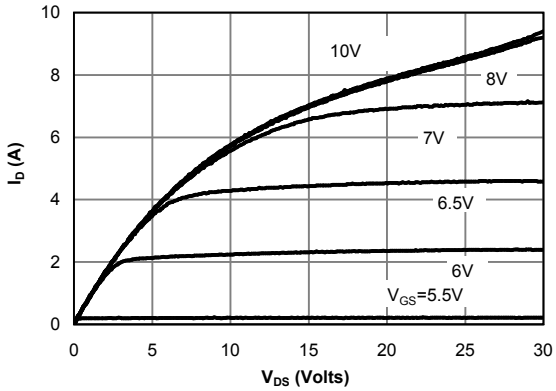


Figure 1: On-Region Characteristics

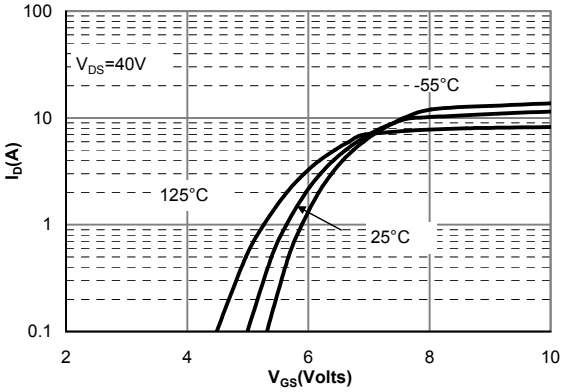


Figure 2: Transfer Characteristics

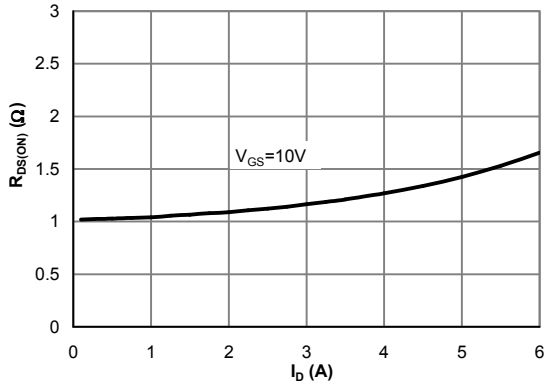


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

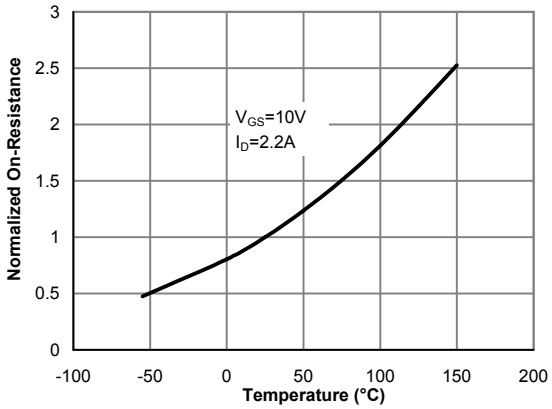


Figure 4: On-Resistance vs. Junction Temperature

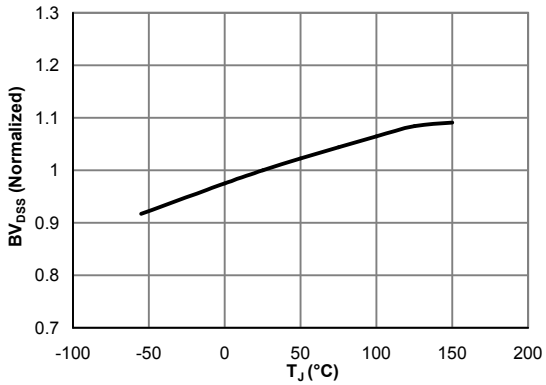


Figure 5: Break Down vs. Junction Temparature

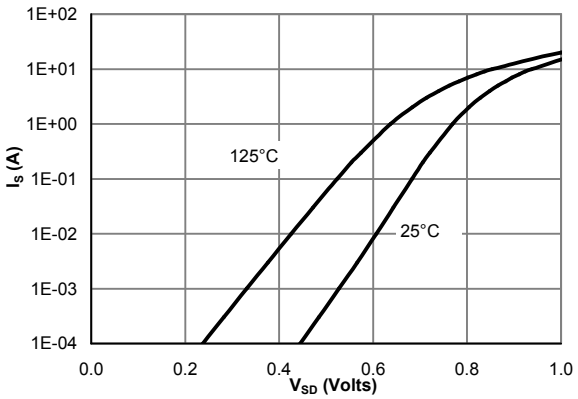


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

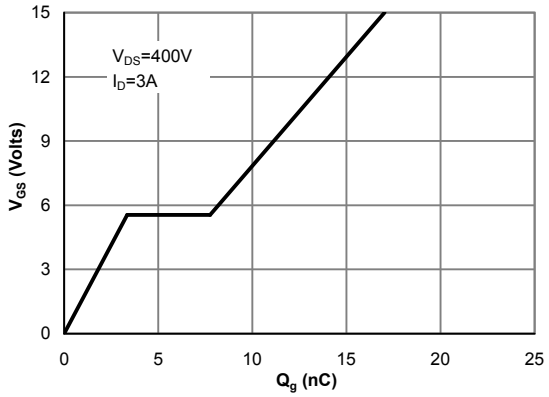


Figure 7: Gate-Charge Characteristics

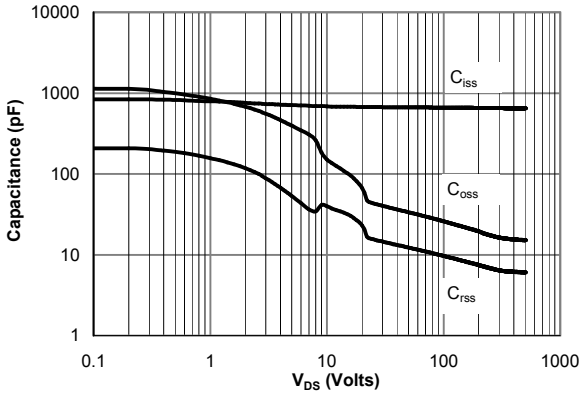


Figure 8: Capacitance Characteristics

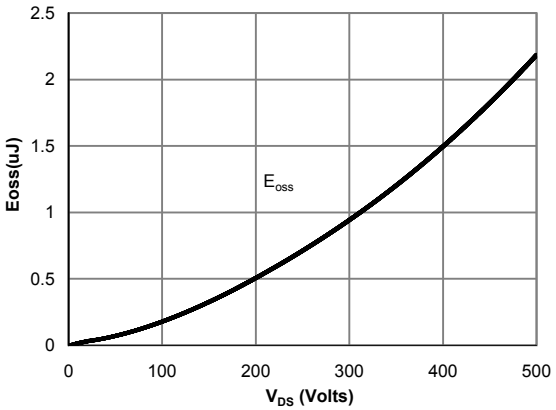


Figure 9: Coss stored Energy

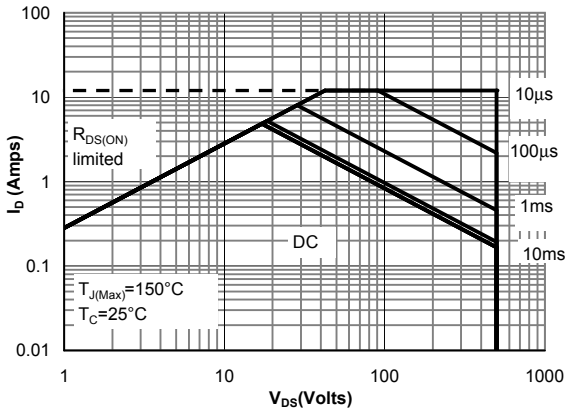


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

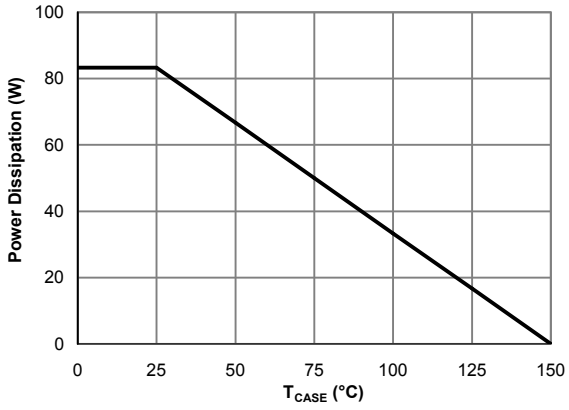


Figure 11: Power De-rating (Note B)

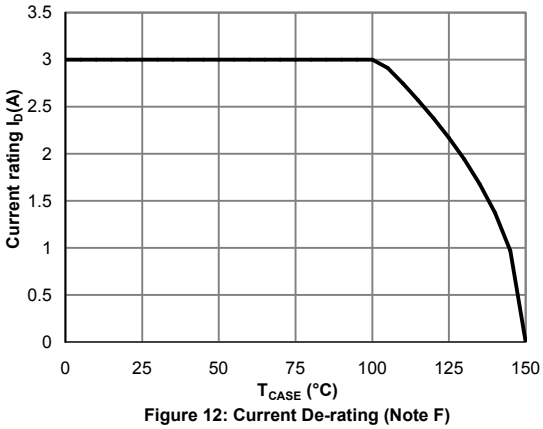


Figure 12: Current De-rating (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

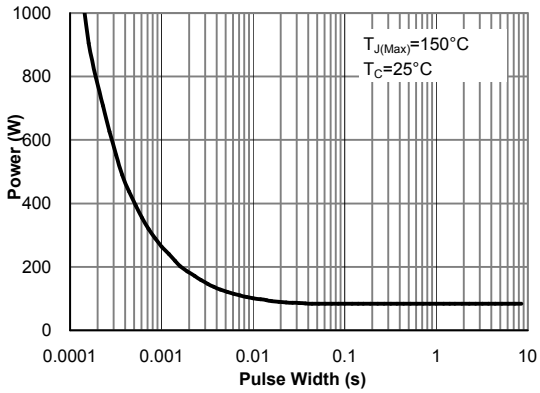


Figure 13: Single Pulse Power Rating Junction-to-Case (Note F)

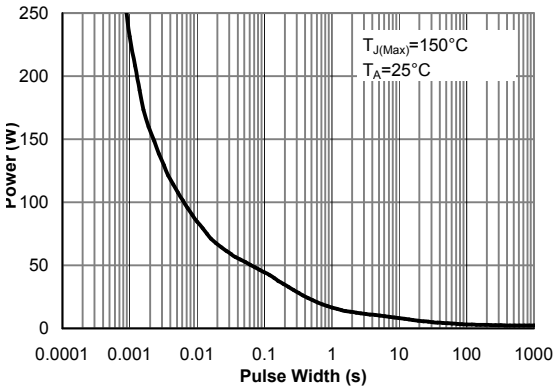


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note G)

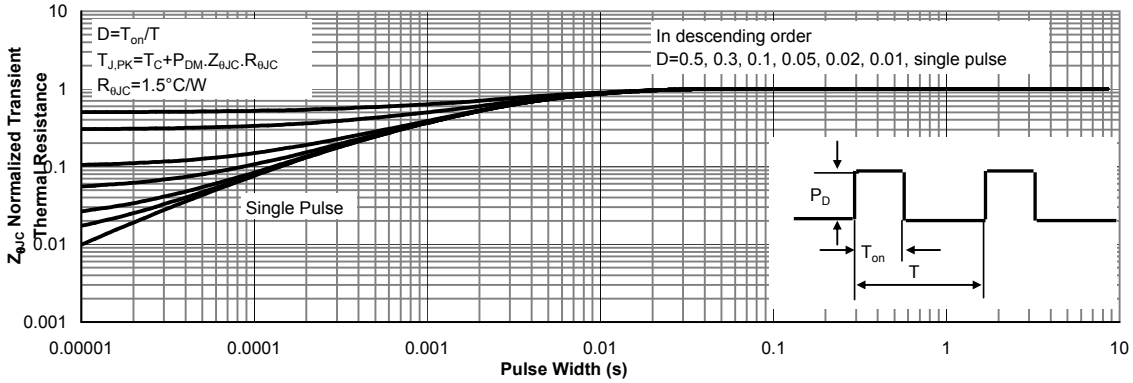


Figure 15: Normalized Maximum Transient Thermal Impedance (Note F)

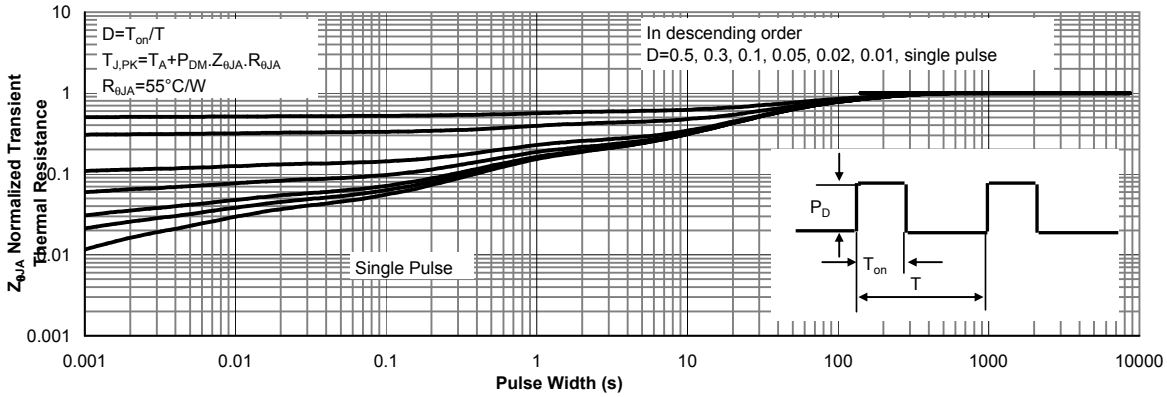
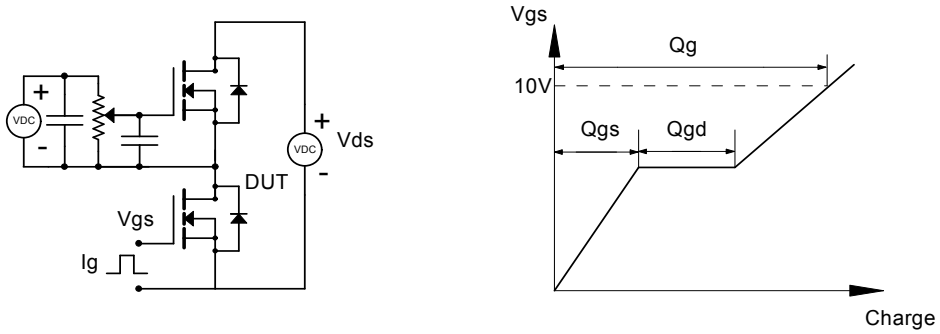
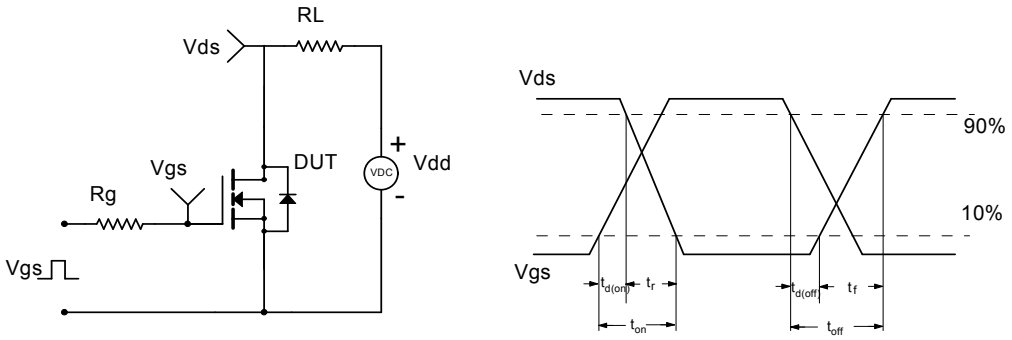


Figure 16: Normalized Maximum Transient Thermal Impedance (Note G)

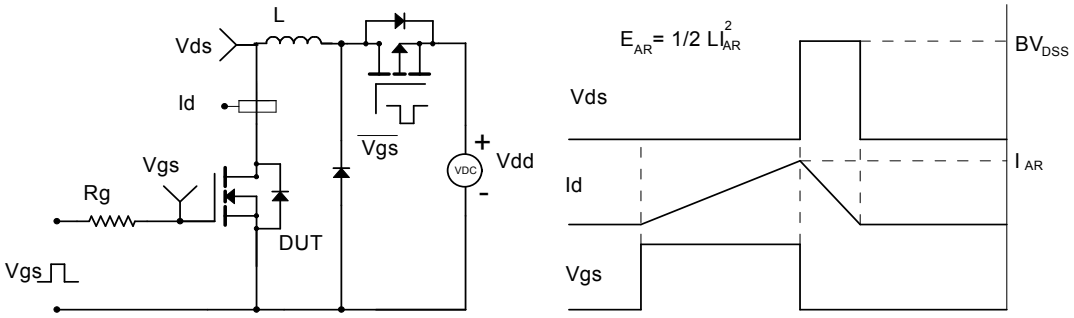
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms